

SEMICONDUCTOR PACKAGE AND METHOD FOR FABRICATING THE SAME

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ABSTRACT OF THE DISCLOSURE

A semiconductor package and method for fabricating the same is disclosed. In one embodiment, the semiconductor package includes a circuit board, at least two semiconductor chips, electric connection means, an encapsulant, and a plurality of conductive balls. The circuit board has a resin layer and a circuit pattern. The resin layer is provided with an opening at its center portion. The circuit pattern is formed on at least one of upper and lower surfaces of the resin layer and includes one or more bond fingers and ball lands exposed to the outside. The semiconductor chips have a plurality of input/output pads on an active surface thereof. The semiconductor chips are stacked at a position of the opening of the circuit board, with at least one of the chips being within the opening. Alternatively, both chips are in the opening. The electric connection means connects the input/output pads of the semiconductor chips to the bond fingers of the circuit board. The encapsulant surrounds the semiconductor chips so as to protect the chips from the external environment. The conductive balls are fusion-bonded on the ball lands of the circuit board.